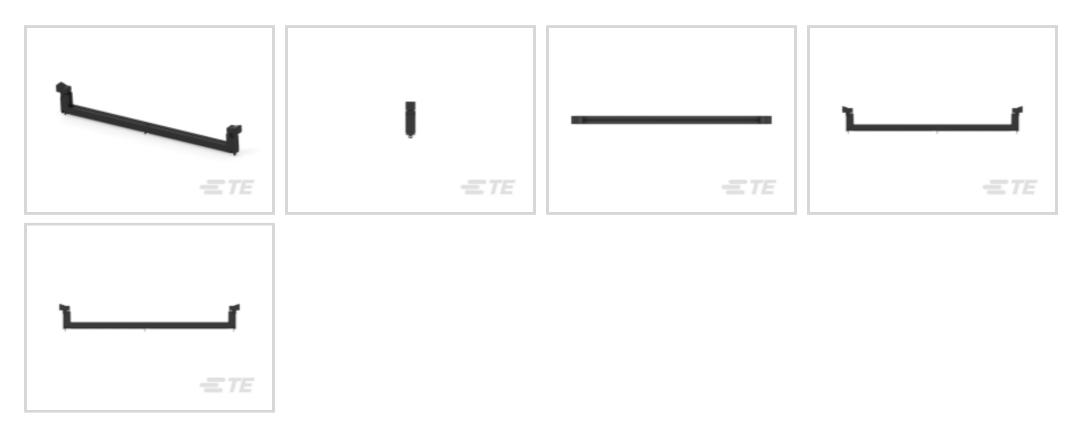
6-2355626-1 <

TE Internal #: 6-2355626-1 Double Data Rate (DDR) 5, Board-to-Component, 288 Position, Surface Mount, Vertical Module Orientation, .85 mm [.033 in] Centerline, DIMM Sockets

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Connectors > Socket Connectors > Memory Sockets > DIMM Sockets



DRAM Type: Double Data Rate (DDR) 5

Connector System: Board-to-Component

Number of Positions: 288

Termination Method to PCB: Surface Mount

Module Orientation: Vertical

Features

Product Type Features



Connector & Contact Terminates To	Printed Circuit Board
DRAM Type	Double Data Rate (DDR) 5
Connector System	Board-to-Component
Configuration Features	
Number of Keys	1
Number of Bays	2
Number of Rows	2
Number of Positions	288
Module Orientation	Vertical
Electrical Characteristics	
DRAM Voltage	1.1 V
Body Features	
Latch Color	Black
Latch Material	High Temperature Nylon

Double Data Rate (DDR) 5, Board-to-Component, 288 Position, Surface Mount, Vertical Module Orientation, .85 mm [.033 in] Centerline, DIMM Sockets



PCB Retention Feature Material	Stainless Steel
Connector Profile	Standard
Ejector Material Color	Black
Module Key Type	DRAM
Ejector Location	Both Ends
Ejector Material	High Temperature Nylon
Ejector Type	Rotary
Contact Features	
Contact Underplating Material	Nickel
Socket Style	DIMM
Contact Mating Area Plating Material Thickness	.76 μm[30 μin]
PCB Contact Termination Area Plating Material Thickness	3 μm[120 μin]
Contact Mating Area Plating Material	Gold (Au)
Memory Socket Type	Memory Card
Contact Base Material	Copper Alloy
PCB Contact Termination Area Plating Material	Tin
Contact Current Rating (Max)	1.5 A

Termination Features

Insertion Style	Direct Insert
Termination Post & Tail Length	.89 mm[.035 in]
Termination Method to PCB	Surface Mount
Mechanical Attachment	
Connector Mounting Type	Board Mount
Mount Angle	Vertical
PCB Mount Retention Type	Таb
Mating Alignment Type	1 Кеу
Mating Alignment	With
PCB Mount Alignment Type	None
Housing Features	
Housing Color	Black
Housing Material	High Temperature Nylon
Centerline (Pitch)	.85 mm[.033 in]

Double Data Rate (DDR) 5, Board-to-Component, 288 Position, Surface Mount, Vertical Module Orientation, .85 mm [.033 in] Centerline, DIMM Sockets



Dimensions

Profile Height from PCB	21.3 mm[.083 in]
Row-to-Row Spacing	3 mm[.118 in]
Usage Conditions	
Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]
Operation/Application	
Circuit Application	High Speed Data
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	640
Packaging Method	Box & Tray
Product Compliance	
For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Compliant

China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Compliant

Solder Process Capability

EU ELV Directive 2000/53/EC

Not reviewed for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

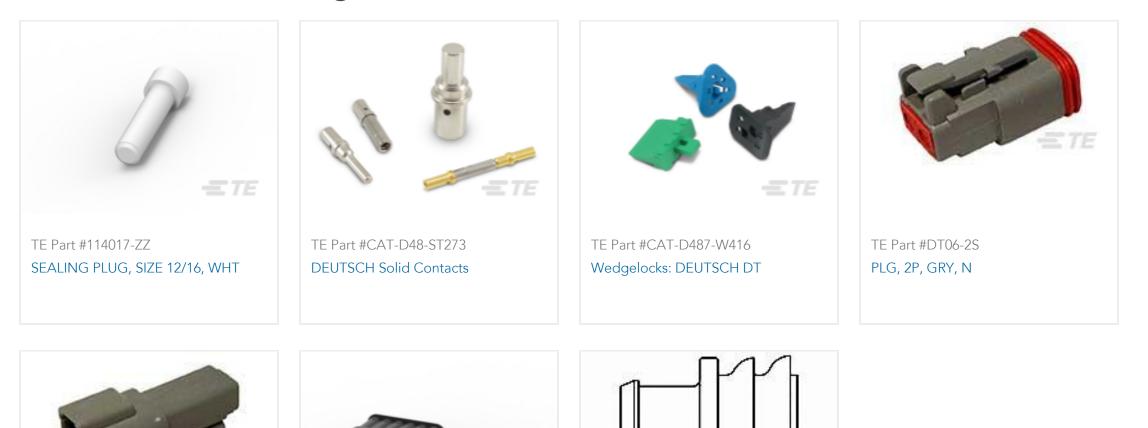
Double Data Rate (DDR) 5, Board-to-Component, 288 Position, Surface Mount, Vertical Module Orientation, .85 mm [.033 in] Centerline, DIMM Sockets



Compatible Parts



Customers Also Bought





Documents

Product Drawings DDR5 DIMM BLACK HSG AND BLACK LATCH

English

CAD Files

Customer View Model

ENG_CVM_CVM_6-2355626-1_A.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_6-2355626-1_A.3d_stp.zip

English

Customer View Model

ENG_CVM_CVM_6-2355626-1_A.3d_igs.zip

English

Double Data Rate (DDR) 5, Board-to-Component, 288 Position, Surface Mount, Vertical Module Orientation, .85 mm [.033 in] Centerline, DIMM Sockets



 3D PDF
 3D

 3D
 Main and Conditions of use.

 Product Specifications
 Application Specification

 English
 English